

Technical Note

Protection Component

LED Drivers for LCD Backlights White Backlight LED Driver for Medium to Large LCD Panels (Switching Regulator Type)

BD6581GU

No.10040EAT13

Description

BD6581GU is white LED driver IC with PWM step-up DC/DC converter that can boost max 42.5V and current driver that can drive max 25mA. The wide and precision brightness can be controlled by external PWM pulse. BD6581GU has very accurate current drivers, and it has few current errors between each strings. So, it will be helpful to reduce brightness spots on the LCD.

Small package type is suited for saving space.

Features

- 1) High efficiency PWM step-up DC/DC converter (fsw=1MHz), max efficiency 93%
- 2) High accuracy & good matching (±1.5%) current drivers 6ch
- 3) Drive up to 12* in series, 6 strings in parallel =72 white LEDs (*white LED Vf=3.5Vmax)
- 4) Wide input voltage range (2.7V ~ 22V)
- 5) Rich safety functions
 - Over-voltage protection (OVP)
 - Over current limit
 - External SBD open detect
 - Thermal shutdown
- 6) Small & thin package (VCSP85H2) 2.6 × 2.6 × 0.85mm

Absolute Maximum Ratings

All middle size LCD equipments backlight of Notebook PC, portable DVD player, car navigation systems, etc.

Parameter	Symbol	Ratings	Unit	Condition
Maximum applied voltage 1	VMAX1	7	V	TEST, VREG, SENSP, SENSN, SW, RSTB, PWMPOW, PWMDRV, FAILSEL, ISETH, ISETL
Maximum applied voltage 2	VMAX2	25	V	LED1, LED2, LED3, LED4, LED5, LED6, VBAT
Maximum applied voltage 3	VMAX3	50.5	V	VDET
Power dissipation 1	Pd1	1100	mW	*1
Operating temperature range	Topr	-30 ~ +85	°C	-
Storage temperature range	Tstg	-55 ~ +150	°C	-

(*1) This value is the measurement value that was mounted on the PCB by ROHM.

Temperature deleting: 8.8mW/ °C from Ta>25°C

●Recommended Operating Range (Ta=-30°C ~ +85°C)

Parameter	Symbol	Limits			Unit	Condition
	Symbol	Min.	Тур.	Max.	Unit	Condition
Power supply voltage	VBAT	2.7	12.0	22.0	V	

●Electrical Characteristic(Unless otherwise specified, VBAT=12V, RSTB=2.5V, Ta = +25 °C)

Parameter	Symbol	Min.	Limits Typ.	Max.	Unit	Condition
[FAILSEL,PWMDRV Terminal]						
EN threshold voltage (Low)	VthL	0	-	0.2	V	
EN threshold voltage (High) 1	VthH1	1.4	-	5.0	V	VBAT>5.0V
EN threshold voltage (High) 2	VthH2	1.4	-	VBAT	V	VBAT<5.0V
EN terminal input current	lin	-	8.3	14.0	μA	Input=2.5V
[PWMPOW Terminal]			1			
Low Input Voltage range	PWML	0	-	0.2	V	
High Input Voltage range1	PWMH1	1.4	-	5.0	V	VBAT>5.0V
High Input Voltage range2	PWMH2	1.4	-	VBAT	V	VBAT<5.0V
PWM pull down resistor	PWMR	300	500	700	kΩ	
[RSTB Terminal]			I		1	I
Low Input Voltage range	RSTBL	0	-	0.2	V	
High Input Voltage range1	RSTBH1	2.25	2.5	5.0	V	VBAT>5.0V
High Input Voltage range2	RSTBH2	2.25	2.5	VBAT	V	VBAT<5.0V
Current Consumption	IRSTB	-	89	134	μA	RSTB=2.5V, LED1-6=3V
[Regulator]			I		1	I
VREG Voltage	VREG	4.0	5.0	6.0	V	No load
Under Voltage Lock Out	UVLO	2.05	2.25	2.65	V	
[Switching Regulator]			I			
Quiescent Current 1	lq1	-	0.6	3.4	μA	RSTB=0V, VBAT=12V
Quiescent Current 2	lq2	-	4.6	10	μA	RSTB=0V, VBAT=22V
Current Consumption	ldd	-	3.4	5.1	mA	VDET=0V,ISETH=24kΩ
LED Control voltage	VLED	0.4	0.5	0.6	V	
Over Current Limit voltage	Оср	70	100	130	mV	*1
SBD Open Protect	Sop	-	-	0.1	V	Detect voltage of VDET pin
Switching frequency	fSW	0.8	1.0	1.2	MHz	
Duty cycle limit	Duty	92.5	95.0	99.0	%	LED1-6=0.3V
Over voltage limit	Ovl	43.0	44.7	46.4	V	LED1-6=0.3V
[Current driver]						I
LED maximum current	ILMAX	-	-	25	mA	
LED current accuracy	ILACCU	-	-	±3	%	ILED=16mA
LED current matching	ILMAT	-	-	±1.5	%	Each LED current/Average (LED1- 6) ILED=16mA
ISET voltage	Iset	0.5	0.6	0.7	V	
LED current limiter	ILOCP	35	60	90	mA	Current limit value at ISET resistance 4.7kΩ setting LED1, 2, 3, 4, 5, 6=0.5V
LED Terminal Over Voltage Protect	LEDOVP	10.0	11.5	13.0	V	RSTB=PWMDRV=2.5V

(*1) This parameter is tested with DC measurement.

Reference Data



Fig.1 Current Consumption vs VBAT



Fig.4 UVLO vs Temperature



Fig.7 LED current vs PWMDRV-HI Duty PWM = 200Hz







Fig.2 Quiescent current vs VBAT



Fig.5 Efficiency vs PWMPOW-HI Duty ISETH=24kΩ, PWM=200Hz



Fig.8 LED current vs PWMDRV-HI Duty (Expansion) PWM = 200Hz



Fig.11 LED current vs PWMPOW-HI Duty (Expansion) PWM = 200Hz



Fig.3 Oscillation frequency vs VBAT



Fig.6 Efficiency vs PWMDRV-HI Duty ISETH=24kΩ, PWM=200Hz



Fig.9 LED current vs PWMDRV-HI Duty PWM = 200Hz, 1kHz,10kHz



Fig.12 LED current vs PWMPOW-HI Duty PWM = 200Hz, 1kHz,10kHz



Fig.22 VOUT@OVP (LED OPEN)

Package Outline



Block Diagram, I/O Equivalent Circuit Diagram



Fig.23 Block diagram



Fig.24 I/O equivalent circuit diagram

Pin Assignment Table

PIN Name	In/Out	PIN Number	Function	Terminal equivalent circuit diagram
A1	VDET	In	Detect input for SBD open and OVP	С
A2	N.C.	-	No connect pin	F
A3	SW	Out	Switching Tr drive terminal	G
A4	SENSP	In	+ Side Current sense terminal	G
A5	SENSN	In	- Side Current sense terminal	А
B1	N.C.	-	No connect pin	F
B3	TEST	In	TEST input (Pull down 100k Ω to GND)	G
B4	ISETH	In	Resistor connection for ,LED current setting at PWMDRV=H	А
B5	GND	-	GND	В
C1	VBAT	In	Battery input	С
C2	PWMPOW	In	PWM input pin for power ON/OFF	E
C3	VREG	Out	Regulator output / Internal power-supply	D
C4	ISETL	In	Resistor connection for ,LED current setting at PWMDRV=L	А
C5	PWMDRV	In	PWM input pin for power ON/OFF only driver	E
D1	RSTB	In	Reset pin L :Reset H :Reset cancel	E
D2	GND	-	GND	В
D3	FAILSEL	In	Latch selectable pin of protect function	E
D4	GND	-	GND	В
D5	LED1	In	Current sink for LED1	С
E1	LED6	In	Current sink for LED6	С
E2	LED5	In	Current sink for LED5	С
E3	LED4	In	Current sink for LED4	С
E4	LED3	In	Current sink for LED3	С
E5	LED2	In	Current sink for LED2	С





Fig.27 10 series x 6parallel LED current 20mA setting Power control PWM application Fig.28 Non-used Inside REG or operating under 5V application

* Please select the capacitor which the little bias fluctuation.

Terminal processing

TEST pin = Connect to GND

N.C. = Nothing specified in particular. Open is recommended.

VREG = When IC is driving from the outside of 2.7~5.5V, short VBAT and VREG, and put the voltage to VREG FAILSEL, PWMDRV = Connect to GND in case of fixing at L level.

- Connect to VREG of IC or the power supply of more than 1.4V in case of fixing at H level .
- LED1-6 = When each LED driver are not used, connect to GND of IC
- GND = Each GND is connecting inside IC, but, connect to GND of all board
- RSTB = RSTB is used as a power supply of internal circuit.

So, you mustn't input RSTB voltage with pull up resistor of several $k\Omega.$

And, please care about the relation between VBAT and RSTB enough.

Description of Functions

1) PWM current mode DC/DC converter

While BD6581GU is power ON, the lowest voltage of LED1, 2, 3, 4, 5, 6 is detected, PWM duty is decided to be 0.5V and output voltage is kept invariably. As for the inputs of the PWM comparator as the feature of the PWM current mode, one is overlapped with error components from the error amplifier, and the other is overlapped with a current sense signal that controls the inductor current into Slope waveform to prevent sub harmonic oscillation. This output controls external Nch Tr via the RS latch. In the period where external Nch Tr gate is ON, energy is accumulated in the external inductor, and in the period where external Nch Tr gate is OFF, energy is transferred to the output capacitor via external SBD. BD6581GU has many safety functions, and their detection signals stop switching operation at once.

2) Soft start

BD6581GU has soft start function.

The soft start function prevents large coil current.

Rush current at turning on is prevented by the soft start function.

After RSTB is changed L \rightarrow H, when PWMPOW is changed L \rightarrow H, soft start becomes effective for within 1ms and soft start doesn't become effective even if PWMPOW is changed L \rightarrow H after that.

And, when the H section of PWMPOW is within 1ms, soft start becomes invalid when PWMPOW is input to H more than three times. The invalid of the soft start can be canceled by making RSTB \rightarrow L.

3) FAILSEL pin

When the error condition occurs, boost operating is stopped by the protection function, and the error condition is avoided. On that occasion, the way to stop of boost operating by the protection function can be selected with FAILSEL pin. Details are as shown in Fig.29, 30.

After power ON, when the protection function is operating under about 1ms have passed, the stop state of the boost operating can be held through FAILSEL is H, the stop state can reset through RSTB is L.

And, boost operating is stopped when the protection function is operating through FAILSEL is L, but when the protection function becomes un-detect, boost operating is started again. It never keeps holding the stop state of boost operating.

In PWM control by PWMDRV can't use this function.

When it is off over 10ms on PWM control by PWMPOW using this function, it may be stopped the boost operating as over current protection work at off on PWMPOW=L.

Object of protect function is as shown below.

- Over-voltage protection
- External SBD open detect
- Thermal shutdown
- LED terminal over-voltage protection
- · Over current limit



Fig.29. FAILSEL operating description

Fig.30. FAILSEL=H light off control

4) External SBD open detect and over voltage protection

BD6581GU has over boost protection by external SBD open and over voltage protection. It detects VDET voltage and is stopped output Tr in abnormal condition. Details are as shown below.

External SBD open detect

In the case of external SBD is not connected to IC, the coil or external Tr may be destructed. Therefore, at such an error as VOUT becoming 0.1V or below, the Under Detector shown in the figure works, and turns off the output Tr, and prevents the coil and the IC from being destructed.

- And the IC changes from activation into non-activation, and current does not flow to the coil (0mA).
- Over voltage protection

At such an error of output open as the output DC/DC and the LED is not connected to IC, the DC/DC will boost too much and the VDET terminal exceed the absolute maximum ratings, and may destruct the IC. Therefore, when VDET becomes sensing voltage or higher, the over voltage limit works, and turns off the output Tr, and the pressure up made stop.

At this moment, the IC changes from activation into non-activation, and the output voltage goes down slowly. And, when the output voltage becomes the hysteresis of the over voltage limit or below, the output voltage pressure up to sensing voltage once again and unless the application error is recovered, this operation is repeated.

5) Thermal shut down

BD6581GU has thermal shut down function.

The thermal shut down works at 175°C or higher, and the IC changes from activation into non-activation. Because non-activation is different from RSTB=L, it doesn't' be reset inside IC. Moreover, even if thermal shut down function works, soft start, FAILSEL, selection the number of LED lines of the current driver and starting current setting at PWMDRV=L related RSTB are hold.

6) Over Current Limit

Over current flows the current detection resistor that is connected to switching transistor source and between GND, SENSP pin voltage turns more than detection voltage, over current protection is operating and it is prevented from flowing more than detection current by reducing ON duty of switching Tr without stopping boost.

As over current detector of BD6581GU is detected peak current, current more than over current setting value does not flow. And, over current value can decide freely by changing over current detection voltage.

<Derivation sequence of detection resistor>

Detection resistor =Over current detection voltage / Over current setting value

TYP value of over current detection voltage is 100mV, MIN = 70mV and MAX = 130mV and after the current value which was necessary for the normal operation was decided, detection resistor is derived by using MIN value of over current detection value.

For example, detection resistor when necessary current value was set at 1A is given as shown below.

Detection resistor =70mV / 1A = 70m Ω

MAX current dispersion of this detection resistor value is

MAX current = $130 \text{mV} / 70 \text{m}\Omega$ = 1.86 A

<The estimate of the current value which need for the normal operation >

As over current detector of BD6581GU is detected the peak current, it have to estimate peak current to flow to the coil by operating condition.

In case of, \circ Supply voltage of coil = VIN $~~\circ$ Inductance value of coil = L

- Switching frequency = fsw
 MIN=0.8MHz, Typ=1MHz, MAX=1.2MHz
- Output voltage = VOUT
 Total LED current = IOUT
- \circ Average current of coil = lave \circ Peak current of coil = lpeak
- Efficiency = eff (Please set up having margin, it refers to data on p.3.)
- ON time of switching transistor = Ton

Ipeak = (VIN / L) x (1 / fsw) x (1-(VIN / VOUT))

```
lave=(VOUT x IOUT / VIN) / eff
```

```
Ton=(lave x (1-VIN/VOUT) x (1/fsw) x (L/VIN) x 2)<sup>1/2</sup>
```

```
Each current is calculated.
```

As peak current varies according to whether there is the direct current superposed, the next is decided.

- (1-VIN/VOUT) x (1/fsw) < Ton \rightarrow peak current = Ipeak /2 + Iave
- $(1-VIN/VOUT) \times (1/fsw) > Ton \rightarrow peak current = Ipeak$

(Example 1)

In case of, VIN=6.5V, L=4.7 μ H, fsw=1MHz, VOUT=39V, IOUT=80mA, Efficiency=85% Ipeak = (6.5V / 4.7 μ H) x (1 / 1MHz) x (1-(6.5V / 39V)) =1.08A Iave = (39V x 80mA / 6.0V) / 85% = 0.61A Ton = (0.61A x (1-6.0V / 39V) x (1 / 1MHz) x (4.7 μ H /6.0V) x 2)^{1/2} = 0.90 μ s (1-VIN/VOUT) x (1/fsw)=0.85 μ s < Ton Peak current = 1.08A/2+0.61A = 1.15A

(Example 2)

In case of, VIN=12.0V, L=4.7µH, fsw=1MHz, VOUT=39V, IOUT=80mA, Efficiency=85% Ipeak = $(12.0V / 4.7µH) \times (1 / 1MHz) \times (1-(12V / 39V)) = 1.77A$ Iave = $(39V \times 80mA / 12.0V) / 85\% = 0.31A$ Ton = $(0.31A \times (1-12 V / 39V) \times (1 / 1MHz) \times (4.7µH / 12 V) \times 2)^{1/2} = 0.41µs$ $(1-VIN/VOUT) \times (1/fsw)=0.69µs > Ton$ Peak current = $12V/4.7µH \times 0.41µs = 1.05A$ *When too large current is set, output overshoot is caused, be careful enough because it is led to break down of the IC in case of the worst.

Operating of the Application Deficiency

1) When 1 LED or 1parallel OPEN during the operating In case of FAILSEL=L, the LED parallel which became OPEN isn't lighting, but other LED parallel is lighting. At that time, output boosts up to the over voltage protection voltage 44.7V so that LED terminal may be 0V or it boost to the output voltage that LED terminal voltage becomes LED terminal over voltage protection 11.5V or it becomes the output voltage restricted by the over current limit.

In case of FAILSEL=H, boost stops when LED becomes OPEN and all LED turns off the lights. 2) When LED short-circuited in the plural In case of FAILSEL=L, all LED is turned on unless LED terminal voltage is LED terminal over voltage protection of more than 11.5V. When it was more than 11.5V only the line which short-circuited is turned on normally and LED current of other lines fall or turn off the lights. In case of FAILSEL=H, boost stops at more than 11.5V and all LED turns off the lights.

- 3) When Schottky diode came off Regardless of FAILSEL, all LED isn't turned on. Also, IC and a switching transistor aren't destroyed because boost operating stops by the Schottky diode coming off protected function.
- 4)When over current detection resistor came off Regardless of FAILSEL, all LED isn't turned on. Because the resistance of 100kΩ is between SENSP and SENSN terminal, over current protection works instantly and LED current can't be flow.

●Control Signal input Timing

2.7V 5V	
VBAT 1	
	Min. 100 µ s 5V
RSTB 3	
PWMPOW	+
PWMDRV	
VREG	
DC/DC VOUT	



Figure.32 Voltage with a control sign higher than VBAT Example corresponding to application of conditions

In case you input control signs, such as RSTB, PWMPOW, and PWMDRV, in the condition that the standup of supply voltage (VBAT) is not completed, be careful of the following point.

①Input each control signal after VBAT exceeds 2.7V.

Figure.31 control Signal timing

2Please do not input each control sign until VBAT exceeds HI voltage of RSTB, PWMPOW, and PWMDRV.

③When you input RSTB during the standup of VBAT and HI voltage is inputted into PWMPOW,

please give the standup time to stable voltage as Min.100µs 2.7V of VBAT.

There is no timing limitation at each input signal of RSTB, PWMPOW and PWMDRV.

If each control sign changes into a condition lower than VBAT in (1) and (2), it goes via the ESD custody diode by the side of VBAT of each terminal. A power supply is supplied to VBAT and there is a possibility of malfunctioning. Moreover, when the entrance current to the terminal exceeds 50mA, it has possibility to damage the LSI. In order to avoid this condition, as shown in the above figure, please insert about 2200hm in a signal line, and apply current qualification. Please confirm an internal pull down resistor in the block diagram and electrical property of P.5.

How to Select the Number of LED Lines of the Current Driver

When the number of LED lines of the current driver is reduced, the un-select can be set the matter that the unnecessary LED1 \sim 6 terminal is connected to GND. When it uses with 4 lines and so on, it can correspond to it by connecting 2 unnecessary lines to GND.

RSTB is used as a power supply of this decision circuit. The select of the terminal is judged, It has no relation to the logic of PWMPOW and PWMDRV and it isn't judged an unnecessary LED line even if it is connected to GND when it is judged a necessary terminal once. This information can be reset by setting RSTB at 0V.

Start Control and Select LED Current Driver

BD6581GU can control the IC system by RSTB, and IC can power off compulsory by setting 0.2V or below. Also, It powers on PWMPOW is at more than 1.4V and RSTB is at more than 2.25V.

When RSTB=PWMPOW=H, ISETH current is selected at PWMDRV=H and ISETL current is selected at PWMDRV=L. The starting current in PWMDRV=L sets OFF second time rise of PWMDRV and it becomes 0mA setting after that.

After RSTB s	ets L once, t	the starting cur	rent can l	be flowed	again by	changing it to H.

RSTB	PWMPOW	PWMDRV	IC	LED current
1	0	0	Off	OFF
1	1	0	On	Starting current decided with ISETL
1	0	1	Off	OFF
1	1	1	On	Current decided with ISETH
0	0, 1	0, 1	Off	OFF

Attendance Point of the Restriction Resistance Input to RSTB

When the restriction resistance is input to RSTB, it is necessary to consider the input current of RSTB. The input current of RSTB changes that depending on the power-supply voltage and the temperature reference to fig.33. Because the temperature characteristic of the input current is shown in fig.33, please choose resistance for which it

Because the temperature characteristic of the input current is shown in fig.33, please choose resistance for which the voltage of the terminal can be guaranteed to 2.1V or more.

And, it has the margin in the decision of resistance, and please confirm and make sure it is no problem in a real application.

The decision example of restriction resistance

- 1. When use the current driver of 6 parallel 2.9V(to RSTB power-supply) - restriction resistance value × 124μ A(100° C input current) > 2.1V restriction resistance value < (2.9-2.1)/124 μ A=6.45k Ω
- 2. When use the current driver of 3 parallel
- 2.9V(to RSTB power-supply) restriction resistance value×430 μ A(100°C input current) > 2.1V restriction resistance value<(2.9-2.1)/430 μ A=1.86k Ω 250



Fig .34 RSTB terminal voltage-RSTB inflow current (At the time of the current driver six lines use)

In addition, the selection number of parallel number of the current driver is changed, the power-supply current of RSTB will be increased.Because the maximum value of the consumption current at the RSTB=2.1V is indicated in the following Table 1, be careful enough when you calculate the restriction resistance.

Table. the use parallel number of current driver a	at RSTB=2.1V , 100°C vs. RSTB	input current
Parallel numbers used for current driver	RSTB input current	
6	0.12mA	
5	0.23mA	
4	0.33mA	
3	0.43mA	
2	0.53mA	
1	0.63mA	
0	0.74mA	

+100°C

Start to Use PWMPOW Terminal for the PWM Control, PWM Operating

After RSTB and PWMDRV is changing L \rightarrow H, input PWM to PWMPOW terminal.

There is no constraint in turn of RSTB and PWMDRV.

And, because it corresponds to PWM drive of shorter ON time than soft start time (1ms), when PWMPOW is input H more than three times, the soft start is invalidated and it enable to correspond the high-speed drive. Until RSTB is set L, invalidation of the soft start isn't canceled.

In case of lighting \rightarrow light off \rightarrow lighting, when it turns off the lights with PWM=L and It starts without soft start when it sets PWM modulated light again.

But the peak current of the coil changes owing to discharge of output capacitor, It may flow to the over current limit value, as follows Fig.35. Because soft start can be used when it turns off the lights with RSTB=L, The peak current of the coil can be suppressed, as follows Fig.36 and this process of light off is recommended.

RSTB ·		
PWMDRV.		
PWMPOW		
Output Voltage		
Current coil		
Fig.35 Light off co	ontrol of PWMPOW pin at PWM contr	ol on PWM=L



Fig.36 Light off control of PWMPOW pin at PWM control on RSTB=L

Start to Use PWMDRV Terminal for the PWM Control, PWM Operating

After RSTB and PWMPOW is changing L \rightarrow H, input PWM to PWMDRV terminal.

There is no constraint in turn of RSTB and PWMPOW.

After RSTB and PWMPOW is changing L \rightarrow H as follows Fig.37, when it is not input PWM to PWMDRV pin but input L, boost of DC/DC is unstable state because current driver doesn't pass current.

The starting current is pulled from each LED terminal and pressure up operating is stabilized to escape from this state.

Also, the starting current can be set up by the resistance value connected to the ISETL terminal.

After starting, as the starting current in PWM brightness control become useless, the starting current is set up 0mA at the second rise time of PWMDRV automatically as follows Fig.37.

In case of lighting \rightarrow light off \rightarrow lighting, when it turns off the lights with PWM=L and It starts without soft start because of soft start period was end when it sets PWM modulated light again.

But the peak current of the coil changes owing to discharge of output capacitor, It may flow to the over current limit value, as follows Fig.38. Because soft start can be used when it turns off the lights with RSTB=L, The peak current of the coil can be suppressed, as follows Fig.39 and this process of light off is recommended.



Fig. 37 Off timing of starting current at PWMDRV=L



Fig.38 Light off control of PWMDRV pin at PWM control on PWM=L



Fig.39 Light off control of PWMDRV pin at PWM control on RSTB=L

Brightness Control

There are two dimming method is available, first method is analog dimming that apply analog voltage to ISET terminal, and second method is PWM control via digital dimming of PWMPOW or PWMDRV. Because each method has the different merit. please choose a suitable method for the application of use.

Two techniques can be used as digital dimming by the PWM control One is PWM control of current driver, the other is PWM control of power control.

As these two characteristics are shown in the below, selects to PWM control process comply with application.

Efficiency emphasis in the low brightness which has an influence with the battery life	\rightarrow 2) Power control PWM control
LED surrent dispersion emphasis in the DW/M brightness control	1) Current driver D\A/A control

LED current dispersion emphasis in the PWM brightness control

Current driver PWM control

(Reference)

PWM regulation process	Efficiency of LED current 0.5mA (PWM Duty=2.5%)	PWM frequency 200Hz Limit dispersion capability of low duty
Current driver	70%	0.2%
Power control	93%	0.5%

1)Current driver PWM control is controlled by providing PWM signal to PWMDRV, as it is shown Fig.25.

The current set up with ISETH is chosen as the Hi section of PWMDRV and the current is off as the Lo section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMDRV signal. This method that it lets internal circuit and DC/DC to work, because it becomes to switch the driver, the current tolerance is a few when the PWM brightness is adjusted, it makes it possible to brightness control until 50µs (MIN1% at 200Hz). And, don't use for the brightness control, because effect of ISETH, ISETL changeover is big under 50us ON time and under 50us OFF time. Typical PWM frequency is 100Hz~10kHz. When RSTB sets H \rightarrow L, so the starting current may be effective, after RSTB sets L→ H, it becomes PWM of the starting current and PWM of ISETH setting current to PWM two times.



2)Power control PWM control is controlled by providing PWM signal to PWMPOW, as it is shown Fig.27. The current setting set up with PWMDRV logic is chosen as the Hi section and the current is off as the Lo section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMPOW signal. This method is, because IC can be power-off at off-time, the consumption current can be suppress, and the high efficiency can be available, so it makes it possible to brightness control until 50µs (MIN1% at 200Hz). And, don't use for the brightness control, because effect of power ON/OFF time changeover is big under 50µs ON time and under 50µs OFF time.

Typical PWM frequency is 100Hz~1kHz. Also, PWM can't control RSTB and PWMPOW at the same time. After RSTB sets H, control PWM only PWMPOW.

PWMPOW	ON	OFF		
LED current	/ ON	OFF	/	
Coil current	ON	OFF		
IC's active current	ON	OFF		

Fig.41

LED Current Setting Range

LED current can set up Normal and Starting setting current.

LED current can set up Normal current by resistance value (RISETH) connecting to ISETH voltage and LED current can set Starting current by resistance value (RISETL) connecting to ISETL voltage.

Setting of each LED current is given as shown below.

Normal current = $20mA(24k\Omega/RISETH)$ Starting constant current = 0.6/RISET L

Also, Normal current setting range is 10mA~25mA, Starting current setting range is OFF setting or 1µA~100µA.

LED current can set OFF setting by open setting ISETL pin.

LED current becomes a leak current MAX 1 μA at OFF setting.

ISETH Normal current setting example				
RISETH	LED current			
24kΩ (E24)	20mA			
25.5 kΩ (E96)	18.8mA			
27 kΩ (E12)	17.8mA			
28kΩ (E96)	17.1mA			
30kΩ (E24)	16.0mA			
33kΩ (E6)	14.5mA			

ISETL Starting current set	tting example
RISETL	LED current
6.2kΩ (E24)	97µA
10kΩ (E6)	60µA
47kΩ (E6)	13µA
100 kΩ (E6)	6µA
560 kΩ (E12)	1.1µA
Connect to VREG pin	0mA

The Separations of the IC Power Supply and Coil Power Supply

This IC can work in separating the power source in both IC power supply and coil power supply. With this application, it can obtain that decrease of IC power consumption, and the applied voltage exceeds IC rating 22V.

That application is shown in below figure 42. The higher voltage source is applied to the power source of coil that is connected from an adapter etc. Next, the IC power supply is connected with a different coil power supply. Under the conditions for inputting from 2.7V to 5.5V into IC VBAT, please follow the recommend design in figure 38. It connects VBAT terminal and VREG terminal together at IC outside.

When the coil power supply is applied, it is no any problem even though IC power supply is the state of 0V. Although IC power supply is set to 0V, pull-down resistance is arranged for the power off which cuts off the leak route from coil power supply in IC inside, the leak route is cut off. And, there is no power on-off sequence of coil power supply and IC power supply.



Fig.42 Application at the time of power supply isolation

The Coil Selection

The DC/DC is designed by more than 4.7μ H. When L value sets to a lower value, it is possibility that the specific sub-harmonic oscillation of current mode DC / DC will be happened.Please do not let L value to 3.3μ H or below. And, L value increases, the phase margin of DC / DC becomes to zero. Please enlarge the output capacitor value when you increase L value.

Example)

4.7μΗ	=	output capacitor	2.2µF/50V	1pcs
6.8µH	=	output capacitor	2.2µF/50V	2pcs
10µH	=	output capacitor	2.2µF/50V	3pcs

This value is just examples, please made sure the final judgment is under an enough evaluation.

Layout

In order to make the most of the performance of this IC, its layout pattern is very important. Characteristics such as efficiency and ripple and the likes change greatly with layout patterns, which please note carefully.



Fig. 43 Layout

Connect the input bypath capacitor $CIN(10\mu F)$ nearest to coil L, as shown in the upper diagram.

Wire the power supply line by the low resistance from CIN to VBAT pin. Thereby, the input voltage ripple of the IC can be reduced. Connect smoothing capacitor CREG of the regulator nearest to between VREG and GND pin, as shown in the upper diagram. Connect schottky barrier diode SBD of the regulator nearest to between coil L and switching transistor Tr. And connect output capacitor COUT nearest to between CIN and GND pin. Thereby, the output voltage ripple of the IC can be reduced.

Connect switching transistor Tr nearest to SW pin. Wire coil L and switching transistor Tr, current sensing resistor R_{SENSE} by the low resistance. Wiring to the SENSP pin isn't Tr side, but connect it from R_{SENSE} side. Over current value may become low when wiring from Tr side. Connect R_{SENSE} of GND side isolated to SENS pin. Don't wire between R_{SENSE} and SNESN pin wiring from R_{SENSE} pin to GND pin. And R_{SENSE} GND line must be wired directly to GND pin of output capacitor. It has the possibility that restricts the current drive performance by the influence of the noise when other GND is connected to this GND. Connect LED current setting resistor RISET nearest to ISET pin. There is possibility to oscillate when capacity is added to ISET terminal, so pay attention that capacity isn't added. And, RISET of GND side must be wired directly to GND pin. When those pins are not connected directly near the chip, influence is given to the performance of BD6581GU, and may limit the current drive performance. As for the wire to the inductor, make its resistance component small so as to reduce electric power consumption and increase the entire efficiency.

Selection of External Parts

Recommended external parts are as shown below.

When to use other parts than these, select the following equivalent parts.

Coil

Value Manufacturer				Size	DC	DCR	
	Product number	Product number Vertical		Height (MAX)	current (mA)	(Ω)	
4.7µH	токо	A915AY-4R7M	5.2	5.2	3.0	1870	0.045
4.7µH	токо	B1015AS-4R7M	8.4	8.3	4.0	3300	0.038
4.7µH	токо	A1101AS-4R7M	4.1	4.1	1.2	1400	0.115
4.7µH	TDK	LTF5022T-4R7N2R0	5.0	5.2	2.2	2000	0.073
4.7µH	TDK	VLP6810T-4R7M1R6	6.3	6.8	1.0	1600	0.167
10µH	TDK	VLP6810T-100M1R1	6.3	6.8	1.0	1100	0.350

Capacitor

Value Pressure	Manufacturar Broduct number	Size			то	Сар		
value	Pressure	Manufacturer	Product number	Vertical	Horizontal	Height	TC	Tol
[Supply v	voltage cap	acitor]						
10µF	25V	MURATA	GRM31CB31E106K	3.2	1.6	1.6 ± 0.2	В	+/-10%
10µF	10V	MURATA	GRM219R61A106K	2.0	1.25	0.85 ± 0.15	X5R	+/-10%
4.7µF	25V	MURATA	GRM319R61E475K	3.2	1.6	0.85 ± 0.1	X5R	+/-10%
4.7µF	25V	MURATA	GRM21BR61E475K	2.0	1.25	1.25 ± 0.1	X5R	+/-10%
[Smooth	ing capacit	or for built-in r	egulator]					
1µF	10V	MURATA	GRM188B10J105K	1.6	0.8	0.8±0.1	В	+/-10%
[Output o	capacitor]							
1µF	50V	MURATA	GRM31MB31H105K	3.2	1.6	1.15 ± 0.1	В	+/-10%
1µF	50V	MURATA	GRM21BB31H105K	2.0	1.25	1.25 ± 0.1	В	+/-10%
2.2µF	50V	MURATA	GRM31CB31H225K	3.2	1.6	1.6±0.2	В	+/-10%
0.33µF	50V	MURATA	GRM219B31H334K	2.0	1.25	0.85±0.1	В	+/-10%
Resistor								

Value	Tolerance	Manufacturer	Product number		Size	
value Tolerance	Manulacturer	FIOUUCLIIUIIDEI	Vertical	Horizontal	Height	
[Resistor	for LED cu	urrent decision	<iseth pin="">]</iseth>			
30kΩ	±0.5%	ROHM	MCR006YZPD303	0.6	0.3	0.23
[Resistor	for over c	urrent decision	<sensp pin="">]</sensp>			
100mΩ	±1%	ROHM	MCR10EZHFSR100	2.0	1.25	0.55
• SBD						

Drogouro	Manufacturer	Product number		Size	
Pressure	Manufacturer	FIOUUCL HUMBER	Vertical	Horizontal	Height
60V	ROHM	RB160M-60	3.5	1.6	0.8
MOS FET	「 Nch	•			

Drocouro	Manufacturer	Droduct number		Size		Current	Driving
Pressure	Manufacturer	Product number	Vertical	Horizontal	Height	Ability	Voltage
45V	ROHM	RTR020N05	2.8	2.9	1.0	2A	2.5V
60V	ROHM	RSS065N06	6.0	5.0	1.75	6.5A	4.0V

The coil is the part that is most influential to efficiency. Select the coil whose direct current resistor (DCR) and current - inductance characteristic is excellent. BD6581GU is designed for the inductance value of 4.7μ H. Doesn't use the inductance value less than 2.2 μ H. Select a capacitor of ceramic type with excellent frequency and temperature characteristics. Further, select Capacitor to be used with small direct current resistance, and pay sufficient attention to the layout pattern shown in P.15.

•Attention point of board layout

In board pattern design, the wiring of power supply line should be low Impedance, and put the bypass capacitor if necessary. Especially the wiring impedance must be lower around the DC/DC converter.

About heat loss

In heat design, operate the DC/DC converter in the following condition. (The following temperature is a guarantee temperature, so consider the margin.)

- 1. Periphery temperature Ta must be less than 85 °C.
- 2. The loss of IC must be less than dissipation Pd.

Notes for use

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Operating conditions These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.

(3) Reverse connection of power supply connector The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.

(4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.

Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(6) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

- (7) Operation in strong electromagnetic field Be noted that using ICs in the strong electromagnetic field can malfunction them.
- (8) Inspection with set PCB

On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.

(9) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

(10) Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.

(11) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(12) Thermal shutdown circuit (TSD)

When junction temperatures become 175°C (typ) or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.

(13) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use.

(14) Selection of coil

Select the low DCR inductors to decrease power loss for DC/DC converter.

Application Example

- LED current setting controlled ISETH resistor. $24k\Omega$: 20mA $30k\Omega$: 16mA $19.6k\Omega$: 24.5mA $33k\Omega$: 14.5mA
- Brightness control

Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic p.3 and function (p.12).



Fig.44 10 series × 6 parallel, LED current 20mA setting Current driver PWM application







Fig.46 8 series × 6 parallel, LED current 20mA setting Current driver PWM application

- LED current setting controlled ISETH resistor. $24k\Omega$: 20mA $30k\Omega$: 16mA $19.6k\Omega$: 24.5mA $33k\Omega$: 14.5mA
- Brightness control Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic p.3 and function (p.12).





7inch panel



Fig.49 8 series × 3 parallel, LED current 20mA setting Current driver PWM application



Fig.48 10 series × 4 parallel, LED current 20mA setting Current driver PWM application



Fig.50 6 series × 4 parallel, LED current 20mA setting Current driver PWM application

- · LED current setting controlled ISETH resistor. 24kΩ : 20mA 30kΩ : 16mA 19.6kΩ : 24.5mA 33kΩ : 14.5mA
- · Brightness control Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic p.3 and function (p.12).

7inch panel

5inch panel



Fig.51 4 series × 6 parallel, LED current 20mA setting Power control PWM application

Battery 8LED x 3 parallel ______Π 10μF 000000000 000000000 00000000 2.2uF* RTR020N05 SW FAILSEL VDET SENSF 68mΩ SENSN Power ON/OFF RSTB 100Hz~1kHz LED1 WMPOW LED2 PWMDRV LED3 VBA LED4 VREG LED5 1µF GND GNDGND GND TEST ISETH ISETL LED6 Each 40mA Can be set up to each 20~50mA

Fig.52 8 series × 3 parallel, LED current 40mA setting Power control PWM application



Fig.53 8 series × 2 parallel, LED current 20mA setting Current driver PWM application



Fig.54 8 series × 2 parallel, LED current 40mA setting Power control PWM application

- LED current setting controlled ISETH resistor. $24k\Omega$: 20mA $30k\Omega$: 16mA $19.6k\Omega$: 24.5mA $33k\Omega$: 14.5mA
- Brightness control
 Dease input PW/M r

Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic p.3 and function (p.12).

5inch panel



Fig.55 4 series × 4 parallel, LED current 20mA setting Current driver PWM application







Fig.56 8 series × 2 parallel, LED current 60mA setting Current driver PWM application

- LED current setting controlled ISETH resistor. $24k\Omega$: 20mA $30k\Omega$: 16mA $19.6k\Omega$: 24.5mA $33k\Omega$: 14.5mA
- Brightness control Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic p.3 and function (p.12).





Fig.60

Control LED current to charged D/A voltage.

Show application example and typ control.

Please decide final value after you evaluated application, characteristic.



Fig.61 Analog style optical application

Ordering part number



VCSP85H2 (BU8920GU)



	copying or reproduction of this document, in part or in whole, is permitted without the nsent of ROHM Co.,Ltd.
The	e content specified herein is subject to change for improvement without notice.
"Pr	e content specified herein is for the purpose of introducing ROHM's products (hereinafte oducts"). If you wish to use any such Product, please be sure to refer to the specifications ich can be obtained from ROHM upon request.
illu	amples of application circuits, circuit constants and any other information contained herein strate the standard usage and operations of the Products. The peripheral conditions mus taken into account when designing circuits for mass production.
Ho	eat care was taken in ensuring the accuracy of the information specified in this document wever, should you incur any damage arising from any inaccuracy or misprint of such prmation, ROHM shall bear no responsibility for such damage.
exa imp oth	e technical information specified herein is intended only to show the typical functions of an amples of application circuits for the Products. ROHM does not grant you, explicitly o plicitly, any license to use or exercise intellectual property or other rights held by ROHM and er parties. ROHM shall bear no responsibility whatsoever for any dispute arising from the e of such technical information.
equ	e Products specified in this document are intended to be used with general-use electronic upment or devices (such as audio visual equipment, office-automation equipment, commu ation devices, electronic appliances and amusement devices).
The	e Products specified in this document are not designed to be radiation tolerant.
	ile ROHM always makes efforts to enhance the quality and reliability of its Products, a oduct may fail or malfunction for a variety of reasons.
aga fail sha	ase be sure to implement in your equipment using the Products safety measures to guard ainst the possibility of physical injury, fire or any other damage caused in the event of the ure of any Product, such as derating, redundancy, fire control and fail-safe designs. ROHM all bear no responsibility whatsoever for your use of any Product outside of the prescribed ope or not in accordance with the instruction manual.
sys ma ins cor of	e Products are not designed or manufactured to be used with any equipment, device o stem which requires an extremely high level of reliability the failure or malfunction of which y result in a direct threat to human life or create a risk of human injury (such as a medica trument, transportation equipment, aerospace machinery, nuclear-reactor controller, fuel- ntroller or other safety device). ROHM shall bear no responsibility in any way for use of any the Products for the above special purposes. If a Product is intended to be used for any ch special purpose, please contact a ROHM sales representative before purchasing.
be	rou intend to export or ship overseas any Product or technology specified herein that may controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to tain a license or permit under the Law.



Thank you for your accessing to ROHM product informations. More detail product informations and catalogs are available, please contact us.

ROHM Customer Support System

http://www.rohm.com/contact/